



**DEPARTMENT OF PHYSICS
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Tender notice no: CBM/AB/Materials/2019-20/Quote5 dated 3rd March 2020

Sealed quotations, along with all supporting documents, are invited from interested vendors for the following items with the specifications given below under the Indo-FAIR Co-ordination Centre project **CBM-MUCH**

Sr.No	Material	Quantity
1	Part no – TPL0501-100DCNR 256-Taps Single-Channel Digital Potentiometer with SPI Interface	100pc
2	OKY-T/5-D12N-C, Adjustable Output 5-Amp DOSA-SMT DC/DC Converters	40pc
3	Part no – SN74LVC1G04YZVR Brief description- Single Inverter Gate	10pc
4	XAL4020-102ME 1 micro Henry inductor	60pc
5	CPC1705Y Single-Pole, Normally Closed 60V, 3.25ADC, 4-Pin Power SIP Relay	20pc
6	CD74HC4067M, High-Speed CMOS Logic 16-Channel Analog Multiplexer/Demultiplexer	15pc
7	OXCORD Twin Flat 2 core Copper Wires and Cables 1.5mm 90 feet (30yard) for Domestic and Industrial Electric Connections Single Phase Electric Connections up to 1100v	1pc
8	10 Sets Female and Male 3.5mm Pitch 2 Pin Way Right Angle Screw Pluggable Terminal Block Plug Connector	6pc
9	INA301A1IDGKR, 36-V, High-Speed, Zero-Drift, Voltage-Output, Current-Shunt Monitor with High-Speed, Overcurrent Comparator	2pc
10	CSD13385F5 12-V N-Channel Femto-FET™ MOSFET	50pc
11	PCB 1 30 cm X 40 cm size 2 layer (PTH V40 min) Gold Plated Contacts 17.5 micron Cu 6 mil track to track and 6 mil pad gapping One layer without green mask (Specified at the time of final order)	5pc
12	PCB2 30 cm X 40 cm size 2 layer (PTH V40 min) Gold Plated Contacts 17.5 micron Cu 6 mil track to track and 6 mil pad gapping One layer without green mask (Specified at the time of final order)	5pc

13	PCB thickness : 2.6 mm Finish : ENIG finish No. of layers : 4 layers PCB size : 29.2cm. X 19.2 cm Material : FR4 PCBs/Panel : Finish Cu Thickness 35.00 um Top Solder Mask : Green Bottom Solder Mask : Green TG - Std. Tg (130-140) Layer Build-Up - Standard Via Fill - No Carbon contacts - No Carbon Contacts UL Logo - No Blind & Buried Via - No Impedance Control - No Electrical Testing - Yes	5pc
14	COM-5403SOFT IP/TCP CLIENT/UDP/ARP/PING STACK with VHDL SOURCE CODE	1
15	Spartan-6 lx9 micro board with Pmod ad1and Pmod da1 modules	8 set
16	Nexys3 Spartan-6 FPGA Board with four Pmod BT2 and 2 PmodWifi	1 set

The sealed quotations must reach the undersigned not later than 17th March 2020, 4pm. The quotations will be opened within 2/3 days from the last date of submission. Quotations received after the deadline will not be considered.

Abhijit Bhattacharyya

(ABHIJIT BHATTACHARYYA)
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